

- Lead Free Finish/RoHS Compliant(Note 1) ("P" Suffix designates RoHS Compliant. See ordering information)

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Features

- High-Speed Switching and High Reverse Breakdown Voltage
- Low Forward Voltage Drop.
- Lead Free Finish/RoHS Compliant (Note1) ("P" Suffix designates RoHS Compliant. See ordering information)

Mechanical Data

- Case: MiniMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Indicated by Cathode Band
- Weight: 0.05 grams (approx.)

Maximum Ratings @ 25°C Unless Otherwise Specified

Characteristic	Symbol	Min	Max	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		75	V
Continuous reverse Voltage	V_R		75	V
Continuous forward current	I_F		200	mA
Repetitive peak Forward Current	I_{FRM}		450	mA
Non-rep. Peak Forward Current $t=1\ \mu\text{s}$ $t=1\ \text{ms}$ $t=1\ \text{s}$	I_{FSM}		4 1 0.5	A
Power Dissipation	P_d		500	mW
Thermal Resistance(Note 2)	R		350	K/W
Operation/Storage Temp. Range	T_j, T_{STG}	-65	200	°C

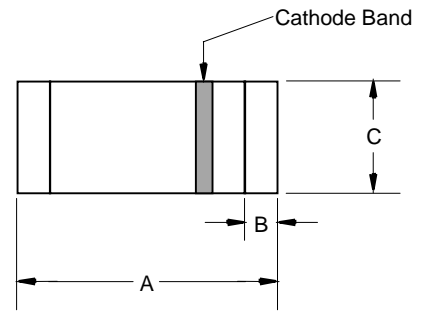
Electrical Characteristics @ 25°C Unless Otherwise Specified

Characteristic	Symbol	Min	Max	Unit	Test Cond.
Reverse Breakdown Volt.	$V_{(BR)R}$	100	-----	V	$I_R=100\ \mu\text{A}$
Reverse Current	I_R	-----	25 5 50 100	nA uA uA	$V_R=20\text{V}$ $V_R=75\text{V}$ $V_R=20\text{V}; T_j=150^\circ\text{C}$ $V_R=75\text{V}; T_j=150^\circ\text{C}$
Forward Voltage	V_F	620 --- ---	750 1000 930	mV mV mV	$I_F=5\text{mA}$ $I_F=100\text{mA}$ $I_F=100\text{mA}; T_j=100^\circ\text{C}$
Junction Capacitance	C_j	-----	2.0	pF	$V_R=0\text{V}, f=1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	-----	4	ns	$I_F=I_R=10\text{mA}$ $I_{r1}=1\text{mA}$ $R_L=100\ \Omega$

- Note: 1. Lead in Glass Exemption Applied, see EU Directive Annex 5.
2. Valid provided that electrodes are kept at ambient temperature
3. Device mounted on an FR4 printed-circuit board.

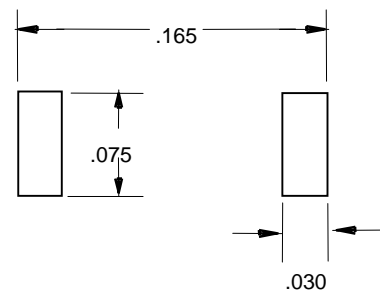
High Speed Switching Diode

MINIMELF

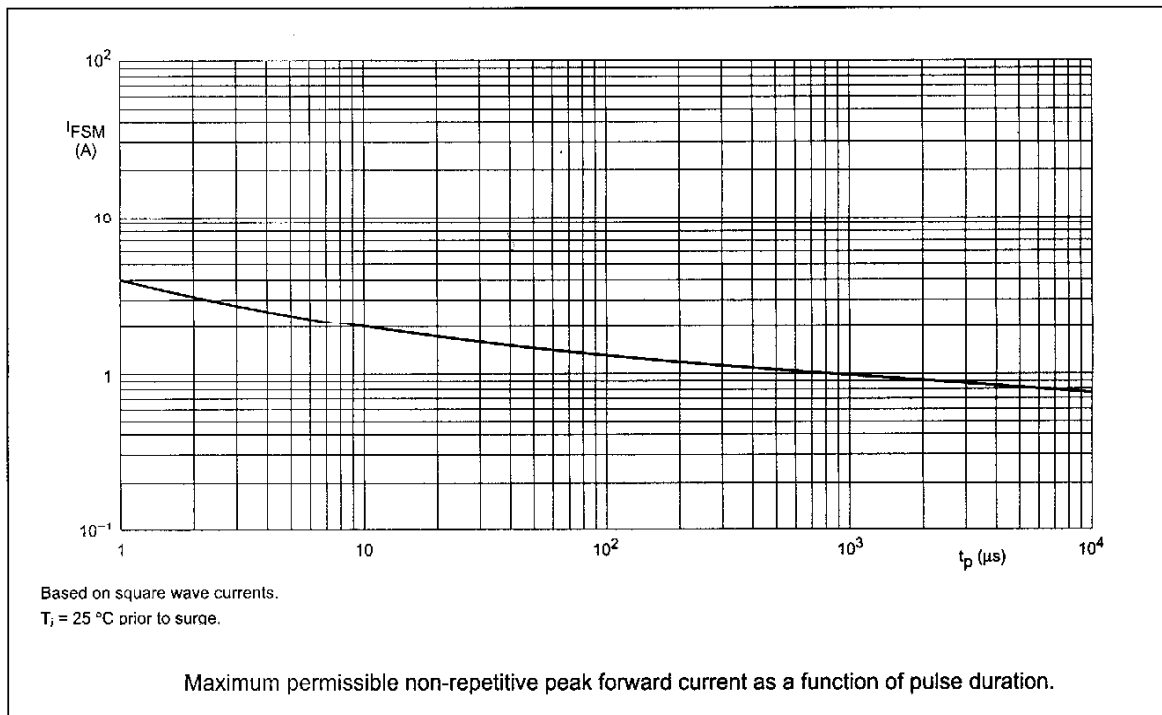
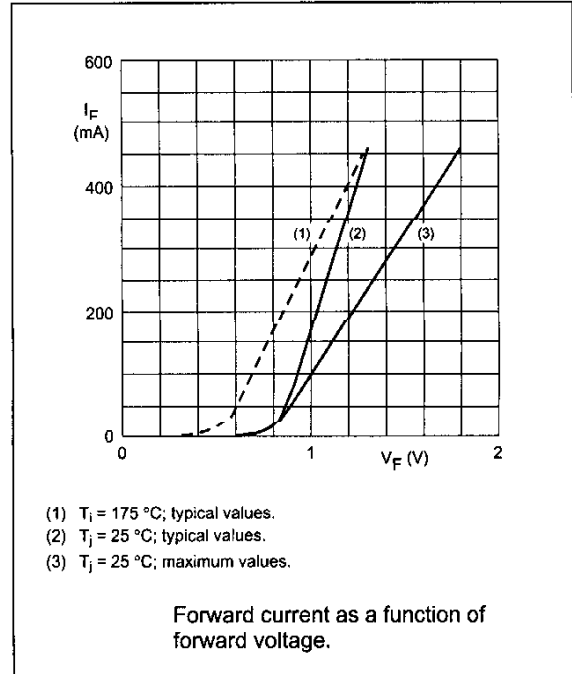
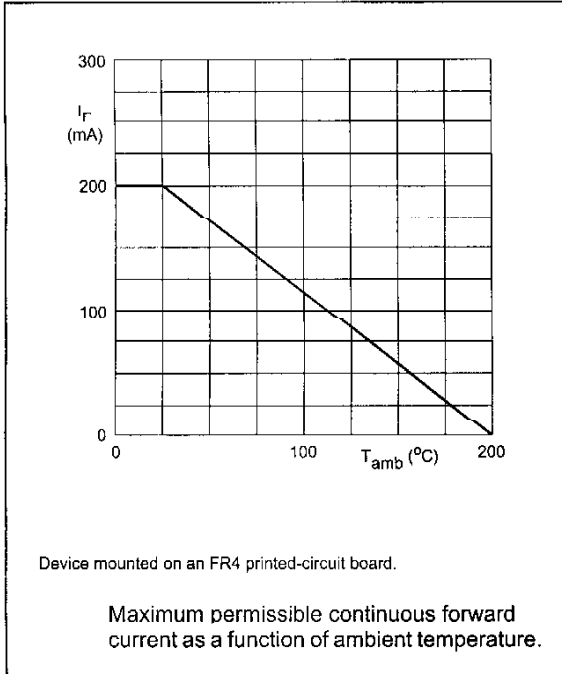


DIM	DIMENSION				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.134	.142	3.40	3.60	
B	.008	.016	0.20	0.40	
C	.055	.059	1.40	1.50	

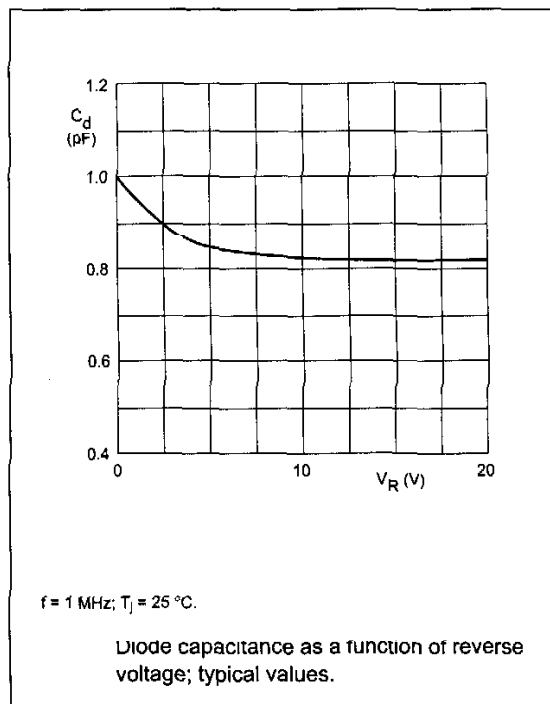
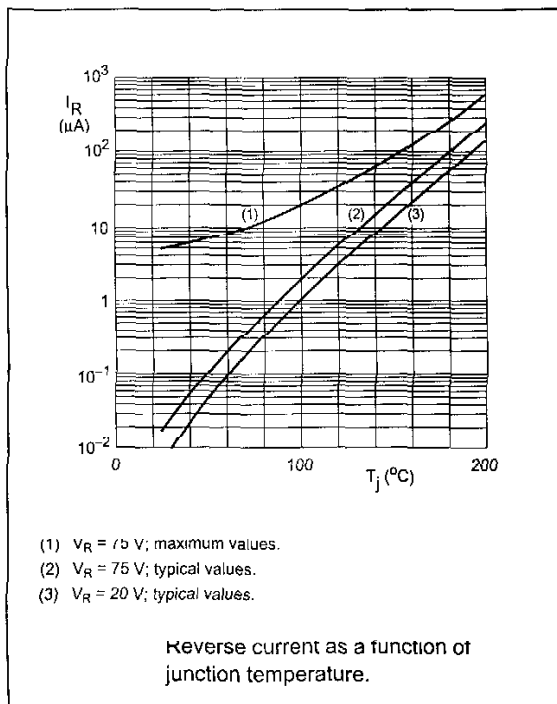
SUGGESTED SOLDER PAD LAYOUT



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Ordering Information

Device	Packing
(Part Number)-TP	Tape&Reel;2.5Kpcs/Reel

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